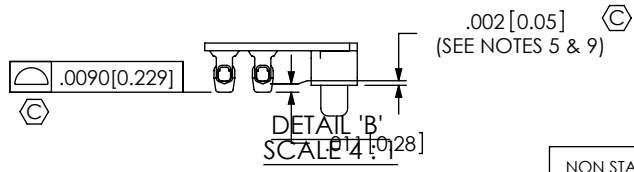
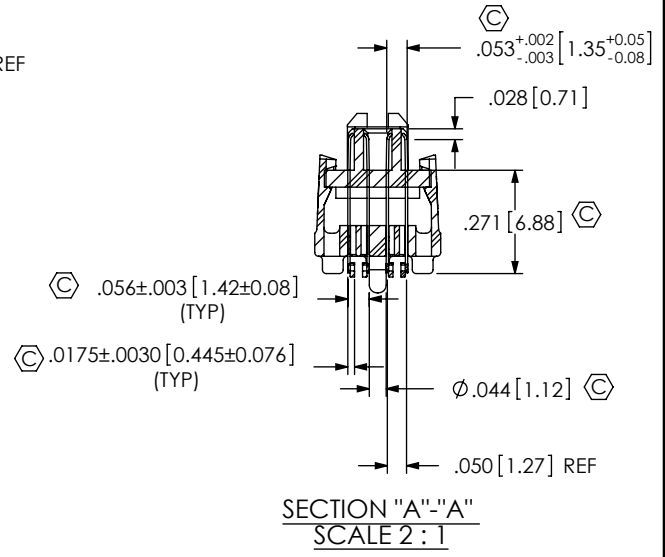
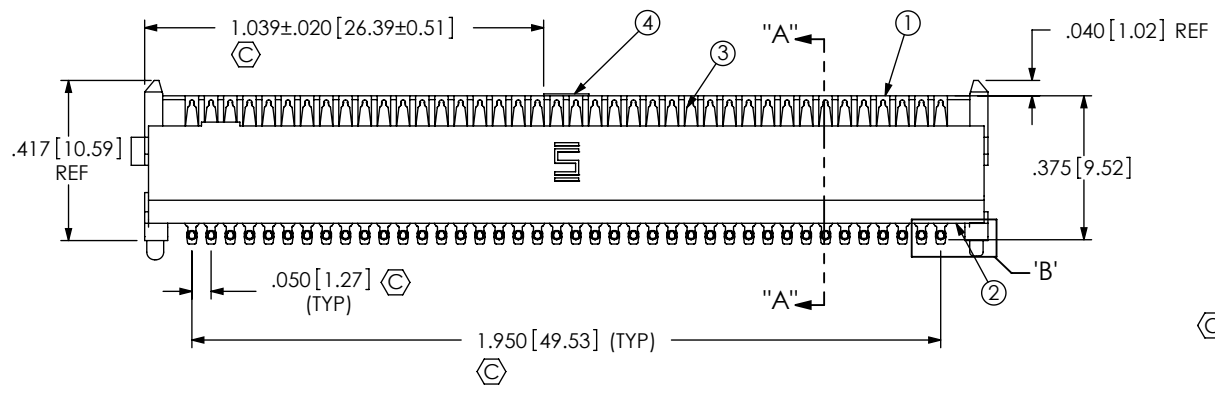
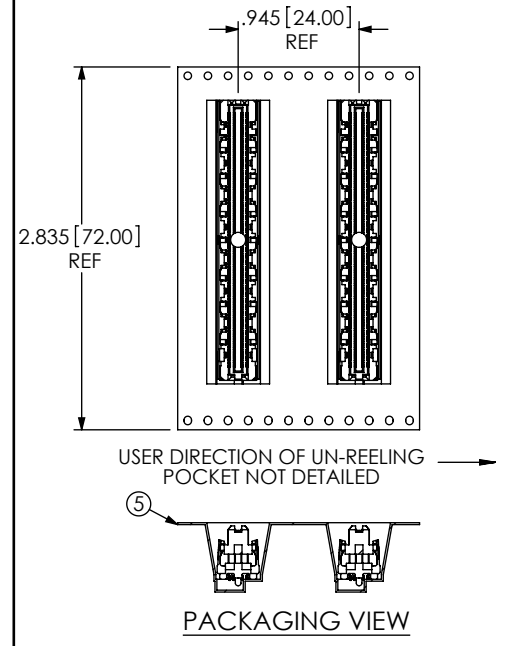
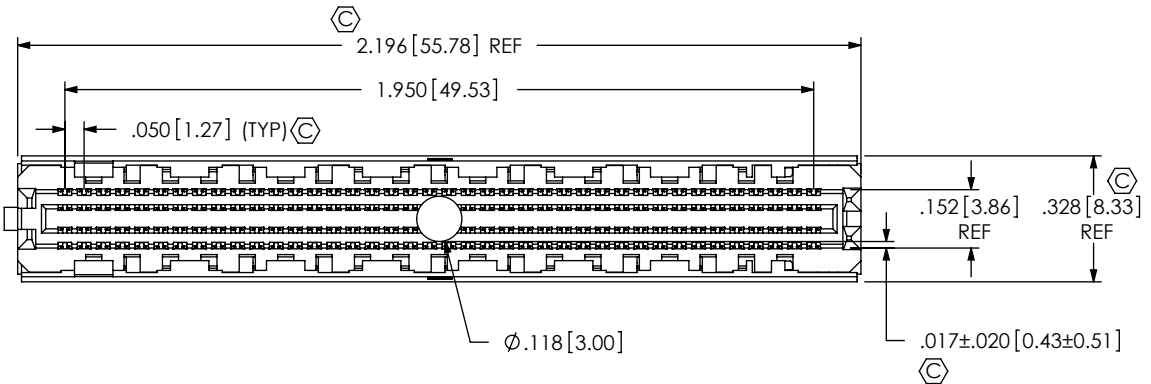


DO NOT SCALE FROM THIS PRINT

- NOTES:
1. STANDARD PART SET UP AS ASP FOR HYPER TRANSPORT STANDARD. PLEASE NOTIFY STANDARDS@SAMTEC.COM FOR PRICING OR DESIGN QUESTIONS
 2. Ⓢ REPRESENTS A CRITICAL DIMENSION.
 3. MAXIMUM CUT FLASH: .010[0.25]
 4. MINIMUM PUSHOUT FORCE: .75 LB.
 5. DIMENSION C8 TO BE MEASURED ON ALL FOUR CORNERS USING INSPECTION FIXTURE AT-1817-836-1. USE CO-AU-WI-2003-M FOR PROCESS.
 6. NOTE DELETED.
 7. NOTE DELETED.
 8. PARTS TO BE PACKAGED IN TAPE & REEL. ATTACH LABEL SEAX-0001 TO EACH TAPE & REEL PACKAGE.
 9. MAXIMUM ROW TO ROW VARIATION: .003[0.10]



ITEM NO.	PART NUMBER	QUANTITY	MATERIAL
1	SEAM-40-00.1-04	1.0000	LCP, UL 94 V0, COLOR: BLACK
2	SEAM-S-40-07.0-04-A	1.0000	LCP, UL 94 V0, COLOR: BLACK
3	NEW-SUB-T1M38-7.0-L-2	160.00	COPPER ALLOY/LEAD FREE SOLDER
4	K-DOT-.138-.250-.005	1.0000	POLYIMIDE FILM
5	CT-SEAM064MS	1.0000	CONDUCTIVE POLYMER

NON STANDARD		UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES. TOLERANCES ARE: DECIMALS ANGLES .XX: ±.01[.3] 2° .XXX: ±.005[.13] .XXXX: ±.0020[.051]	PROPRIETARY NOTE THIS DOCUMENT CONTAINS INFORMATION CONFIDENTIAL AND PROPRIETARY TO SAMTEC, INC. AND SHALL NOT BE REPRODUCED OR TRANSFERRED TO OTHER DOCUMENTS OR DISCLOSED TO OTHERS OR USED FOR ANY PURPOSE OTHER THAN THAT WHICH IT WAS OBTAINED WITHOUT THE EXPRESSED WRITTEN CONSENT OF SAMTEC, INC.
COMPONENT			
ASSEMBLY			
TOOLING			
PROCESS			
PACKAGING		PLATING: DO NOT SCALE DRAWING SHEET SCALE: 1:1 CONTACT AREA: .000040 GOLD OVER .000050 NICKEL REMAINDER: .000200 REF TIN OVER .000050 NICKEL	
OTHER	X	LEAD FREE SOLDER	

520 PARK EAST BLVD, NEW ALBANY, IN 47150
 PHONE: 812-944-6733 FAX: 812-948-5047
 e-Mail: info@SAMTEC.com code 53322

DESCRIPTION:
.050 PITCH TERMINAL ARRAY ASSEMBLY

DWG. NO. **ASP-151797-02-07.0**

BY: J. BROWNING 02/15/2010 SHEET 1 OF 1